

#5100510470

Docket No.: GR 97 P 1903

jc135 U.S. PTO
09/483737
01/14/00



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : HANSJÖRG REICHERT ET AL.

Filed : Concurrently herewith

Title : METHOD AND APPARATUS FOR PRODUCING A CHIP-SUBSTRATE CONNECTION

INFORMATION DISCLOSURE STATEMENT

Hon. Commissioner of Patents and Trademarks,
Washington, D.C. 20231

Sir:

In accordance with 37 C.F.R. 1.98 copies of the following patents and/or publications are submitted herewith:

U.S. Patent No. 4,214,904 (Kitchen et al.), dated July 29, 1980;

U.S. Patent No. 4,875,617 (Citowsky), dated October 24, 1989;

German Published, Non-Prosecuted Application No. 195 32 250 A1 (Wilde et al.), dated March 6, 1997, pertains to a configuration and method for diffusion soldering of a multi-layer construction;

Published European Patent Application No. 0 517 369 A1 (Parker et al.), dated December 9, 1992;

"A low temperature bonding process using deposited gold-tin composite", Chin C. Lee et al., Thin Solid Films, February 1992, No. 2, Lausanne, Switzerland, pp. 202-209;

"Au-Sn alloy phase diagram and properties related to its use as a bonding medium", Goran S. Matijasevic et al., Thin Solid Films, February 1993, No. 2, Lausanne, Switzerland, pp. 276-287;

"A New Gold-Tin Alloy Composition for Hermetic Package Sealing and Attachment of Hybrid Parts", D.D. Zimmerman, Solid State Technology, Vol. 15, No. 1, January 1972, pp. 44-46;

"Alternative Lotwerkstoffe für Elektronikbaugruppen", Hans-Jürgen Albrecht, Siemens-Zeitschrift Special, 1996, pp. 14-16, pertains to alternative soldering materials for electronic component groups;

"A New Bonding Technology Using Gold and Tin Multilayer Composite Structures",
Chin C. Lee et al., IEEE Transactions on Components, Hybrids, and Manufacturing
Technology, Vol. 14, No. 2, June 1991, pp. 407-412;

Japanese Patent Abstract No. 54022164, dated February 19, 1979, from Derwent
Publication No. XP-002082510;

Japanese Patent Abstract No. 54022162, dated February 19, 1979, from Derwent
Publication No. XP-002082511;

Japanese Patent Abstract No. 55006839 (Hiroshi), dated January 18, 1980 and

Japanese Patent Abstract No. 01239982 (Tatsuya), dated September 25, 1989.

If no translation of pertinent portions of any foreign language patents or publications
mentioned above is included with the aforementioned copies of those applications,
patents and/or publications, it is because no existing translation is readily available to
the applicant.

Respectfully submitted,



For Applicants

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Date: January 14, 1999

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FORM PTO-1449 (SUBSTITUTE)			Attorney Docket No.: GR 97 P 1903	Appl. No.
U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE			Applicant HANSJÖRG REICHERT ET AL.	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (37 CFR 1.98(b))			Filing Date JANUARY 14, 2000	Group Art Unit

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EXAMINER INITIALS		PATENT NO.	DATE	PATENTEE	CLASS	SUB CLASS	FILING DATE
<i>A.S.</i>	A	4,214,904	07/80	Kitchen et al.			
<i>A.S.</i>	B	4,875,617	10/89	Citowsky			
	C						
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	I						

FOREIGN PATENT DOCUMENT

		DOCUMENT NO.	DATE	COUNTRY	CLASS	SUB CLASS	TRANSL. YES NO
	J	19532250A1	03/97	Germany			X
	K	0517369A2	12/92	Europe			X
	L						
	M						
	N						

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

<input checked="" type="checkbox"/>	"A low temperature bonding process using deposited gold-tin composite", Chin C. Lee et al., Thin Solid Films, February 1992, No. 2, Lausanne, Switzerland, pp. 202-209
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EXAMINER	DATE CONSIDERED
<i>A.S.</i>	<i>1.8.03</i>

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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AS	<input checked="" type="checkbox"/>	Japanese Patent Abstract No. 54022164, dated February 19, 1979, from Derwent Publication No. XP-002082510

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A.C.	<input checked="" type="checkbox"/>	Japanese Patent Abstract No. 01239982 (Tatsuya), dated September 25, 1989

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